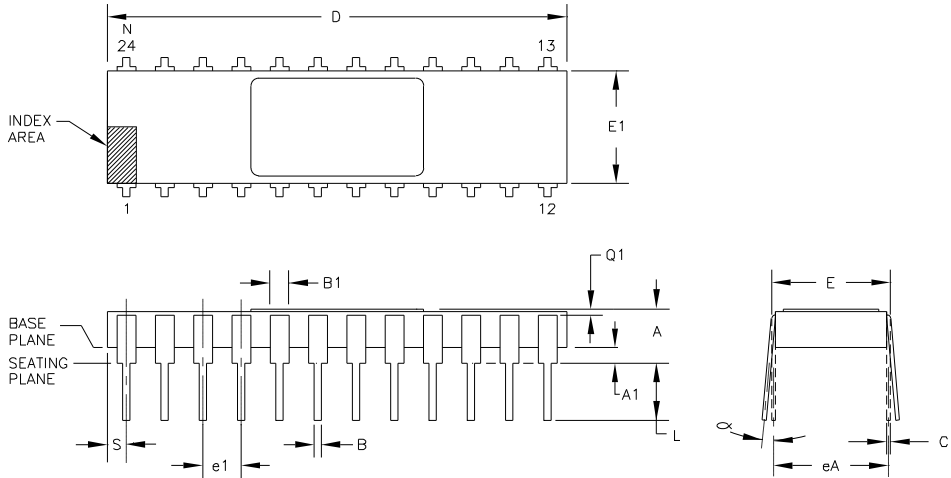


Package Number 245 - 24-Lead, Ceramic Side Braze DIP, .300 Wide



DIM	INCHES		MILLIMETERS		N O E	DIM	INCHES		MILLIMETERS		N O E
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	.105	.175	2.67	4.45		α	0°	15°	0°	15°	3
A1	.025	.055	0.64	1.40							
B	.015	.021	0.38	0.53	5						
B1	.038	.060	0.97	1.52	5						
C	.008	.012	0.20	0.30							
D	1.188	1.212	30.18	30.78							
E	.290	.325	7.37	8.26							
E1	.280	.310	7.11	7.87	6						
e1	.100 TYP.		2.54 TYP.		2						
eA	.300 TYP.		7.62 TYP.		2						
L	.125	.175	3.18	4.45							
N	24		24		4						
Q1	.010	--	0.25	--							
S	.030	.065	0.76	1.65							

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5-1973.
 2. LEADS WITHIN .005 IN. (0.13mm) RADIUS OF TRUE POSITION (TP) AT GAUGE PLANE WITH MAXIMUM MATERIAL CONDITION AND UNIT INSTALLED.
 3. α APPLIES TO SPREAD LEADS PRIOR TO INSTALLATION.
 4. N IS THE NUMBER OF TERMINAL POSITIONS.

5. OUTLINES ON WHICH THE SEATING PLANE IS COINCIDENT WITH THE PLANE ($A1 = 0$), TERMINALS LEAD STANDOFFS ARE NOT REQUIRED, AND B1 MAY EQUAL B ALONG ANY PART OF THE LEAD ABOVE THE SEATING/BASE PLANE.
6. E1 DOES NOT INCLUDE PARTICLES OF PACKING MATERIALS.
7. CONTROLLING DIMENSION: INCH.
8. A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE CROSS-HATCHED AREA.

PACKAGE NUMBER: Z2245 REV.: C
 JEDEC NUMBER: MO-36-AE
 WITH THE EXCEPTION OF DIM. D, N



PACKAGE DRAWING

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